

ABC

Aluminium Between Copper Foil

A simple solution for Multilayer Lamination

ABC is a combination of Copper/Aluminium which have been bonded together using an ultrasonic process. ABC product is produced and marketed solely by the ELTECH Group. This product is available in various sizes with wide range of Copper combined with high-grade Aluminium separator foils.

BENEFITS

- | | |
|-------------------------------|---|
| •Higher first pass yields | Outerlayer circuit surfaces protected from air Particulate during the lay up process, thus ensuring That they are free from resin spots and dust |
| •Handling problems eliminated | no wrinkles in copper, related defects also greatly reduced
No issues with registration and handling of thin Copper foils (9µm,12 µm, 18 µm, 35 µm) |
| •Increase press capacity | The number of boards per daylight can be increased significantly (>30%) |

ELTECH Group CONTACT

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ABC

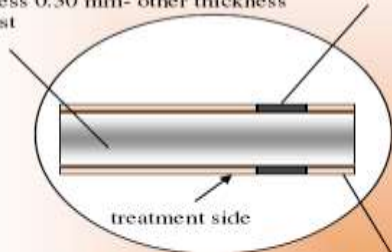
Aluminium Between Copper Foil

SPECIFICATIONS

CONSTRUCTION

ALUMINIUM

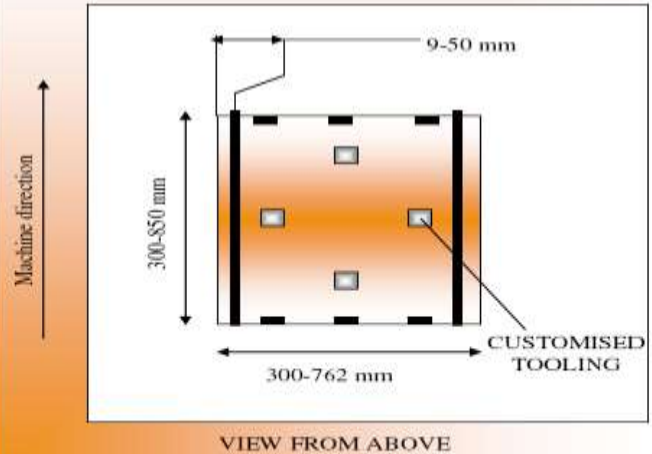
- Highly controlled surface hardness **ULTRASONIC**
- Mg alloy grade ($R_m > 320 \text{ N/mm}^2$) **WELDING**
- Thickness 0.30 mm- other thickness on request



COPPER FOILS

- ABC is exclusively built with Copper Foil in accordance with IPC 4562 Class 3 HTE
- Thickness range from 9μ to 35μ

PANEL CAPABILITY



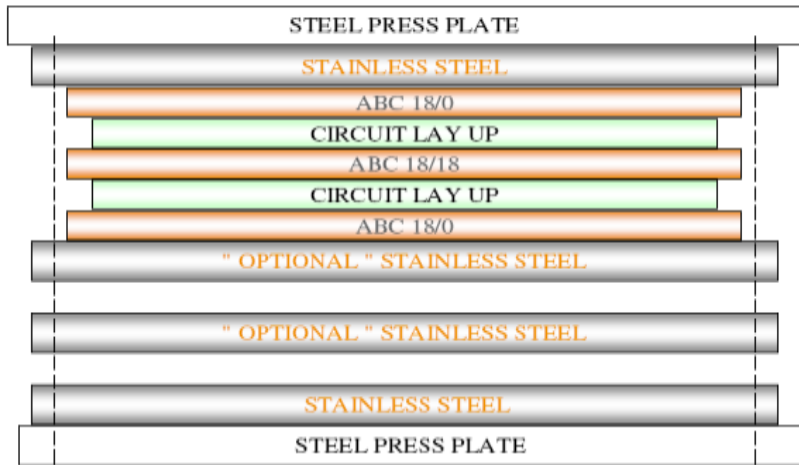
PROCESSING

Example : 15 panels/opening instead of 11 when using steel (circuit thickness = 1.5 mm)

5 MLB

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ORDERING INFORMATION



5. Punched
4. Copper foil bottom
3. Copper foil top
2. Aluminium thickness
1. Product reference